Title (en)

ADHESIVE CONDUCTIVE PASTE

Title (de)

KLEBENDE LEITFÄHIGE PASTE

Title (fr)

PÂTE CONDUCTRICE DE LIAISON

Publication

EP 4012726 A1 20220615 (EN)

Application

EP 20850274 A 20200804

Priority

- JP 2019145510 A 20190807
- JP 2020029758 W 20200804

Abstract (en)

An object of the present disclosure is to provide a paste that can suppress fluctuations in viscosity at a printing temperature to perform printing without unevenness, and is sintered fast even in an inert gas atmosphere such as nitrogen to form a highly accurate conductive wiring and a joined structure excellent in joining strength. The present disclosure provides an adhesive conductive paste for forming a conductive wiring and/or a joined structure to connect electronic elements, the adhesive conductive paste including a conductive particle and a solvent. The adhesive conductive paste contains, as the conductive particle, a silver particle (A) having an average particle size of 1 nm or greater and less than 100 nm and a silver particle (B) having an average particle size of 0.1 μm or greater and 10 μm or less, the silver particle (A) being a silver nanoparticle having a configuration in which a surface is coated with a protective agent containing amine, andthe adhesive conductive paste contains, as the solvent, a compound (C) represented by Formula (I) below: Ra-O-(X-O)_n-R^b ... (I)where in Formula (I), R^a represents a monovalent group selected from a hydrocarbon group having from 1 to 6 carbon atom(s) and an acyl group, X represents a divalent group selected from a hydrocarbon group having from 2 to 6 carbon atoms, R^b represents a hydrogen atom or a monovalent group selected from a hydrocarbon group having from 1 to 6 carbon atom(s) and an acyl group, R^aand R^b may be the same, n represents an integer from 1 to 3.

IPC 8 full level

H01B 1/22 (2006.01); **H05K 3/10** (2006.01)

CPC (source: EP KR US)

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Designated contracting state (EPC)

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EP 4012726 A1 20220615; **EP 4012726 A4 20230823**; CN 114270453 A 20220401; JP WO2021025003 A1 20210211; KR 20220042428 A 20220405; TW 202113876 A 20210401; US 2022275247 A1 20220901; WO 2021025003 A1 20210211

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